

제23회 한국반도체학술대회

2016년 2월 22일(월)-24일(수), 강원도 하이원리조트

A. Interconnect & Package 분과

Room A
태백 I (5층)

2016년 2월 23일(화) 15:10-17:10

[TA3-A] A2: Enabling Packaging Technologies

좌장 : 김사라은경(서울과학기술대학교), 이웅선(SK 하이닉스)

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| TA3-A-1 | 15:10-15:25 | Microstructural Influence in Stress and Reliability Engineering for 3D Interconnect Systems
Hojin Lee, Jinho An, Kwangjin Moon, Byung Lyul Park, Nae-in Lee, Siyoung Choi, Ho-Kyu Kang, and E.S. Chung
<i>Samsung Semiconductor R & D Center, Samsung Electronics Co., Ltd.</i> |
| TA3-A-2 | 15:25-15:40 | Fabrication and Characterization of Sn-58Bi-xCe Nanoscale solder powder using Electrical Wire Explosion Method
Jae-Oh Bang and Seung-Boo Jung
<i>School of Advanced Materials Science and Engineering, Sungkyunkwan University</i> |
| TA3-A-3 | 15:40-15:55 | Electrical and Mechanical Properties of Reverse-offset Printed Sn-Ag-Cu Solder Bump
Min-Jung Son ^{1,2} , Minwoo Kim ¹ , Taik-Min Lee ¹ , Hoo-Jeong Lee ¹ , and Inyoung Kim ¹
¹ <i>Department of Printed Electronics, Korea Institute of Machinery & Materials, ²School of Advanced Materials Science and Engineering, Sungkyunkwan University</i> |
| TA3-A-4 | 15:55-16:10 | Reliability of Flip-chip and Wire Bonding in System-in-Package(SiP)
Woo-Ram Myung ¹ , Jae-Oh Bang ² , and Seung-Boo Jung ²
¹ <i>SKKU Advanced Institute of Nanotechnology (SAINT), Sungkyunkwan University, ²School of Advanced Materials Science & Engineering, Sungkyunkwan University</i> |
| TA3-A-5 | 16:10-16:25 | The Influence of Intermetallic Compound on the Reliability of Flip-Chip Light Emitting Diode Package
Kwong-Ho Jung ¹ , Bum-Geun Park ² , and Seung-Book Jung ¹
¹ <i>Department of Advanced Materials Science & Engineering, Sungkyunkwan University, ²SKKU Advanced Institute of Nanotechnology, Sungkyunkwan University</i> |
| TA3-A-6 | 16:25-16:40 | Timing Exception Path Masking Program
Tae Hyun Kim, Hyunyul Lim, and Sungho Kang
<i>Department of Electrical and Electronic Engineering, Yonsei University</i> |
| TA3-A-7 | 16:40-16:55 | 테스트 병렬성 확대를 위한 SoC 자가 테스트 방법론
임현찬, 서성열, 강성호
<i>Department of Electrical and Electronics Engineering, Yonsei</i> |

The 23rd Korean Conference on Semiconductors (KCS 2016)

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University

TA3-A-8 16:55-17:10 은 인쇄전자회로의 전기화학적 자가복원
정광호¹, 이유림¹, 김승현¹, 이수경¹, 정상용², 정승부¹
¹성균관대학교 신소재공학부, ²성균관대학교 화학공학부